

Freescale Semiconductor

Application Note

Document Number: AN2975 Rev. 1.0 , 02/2007

Range Extension for IEEE[®] 802.15.4 and ZigBee[™] Applications

1 Introduction

The Freescale series of ZigBeeTM transceivers, which includes the MC1319x, MC1320x, and MC1321x, are IEEE[®] 802.15.4 Standard compliant, 2.4 GHz Industrial, Scientific, and Medical (ISM) band transceivers. Typical intended applications include, but are not limited to the following:

- Remote control and wire replacement in industrial systems such as wireless sensor networks
- Factory automation and motor control
- Energy Management (lighting, HVAC, etc.)
- Asset tracking and monitoring
- Home automation and control (lighting, thermostats, etc.)
- Human interface devices (keyboard, mice, etc.)
- Remote entertainment control
- Wireless toys

To extend the functionality of these devices into other application spaces, it is possible to trade low power consumption for range by adding an external Power

© Freescale Semiconductor, Inc., 2005, 2006, 2007. All rights reserved.

Contents

1	Introduction 1
2	General Requirements 2
3	Practical Test Implications 8
4	Device Examples9
5	Modules





Amplifier (PA) and/or a Low Noise Amplifier (LNA). This note provides general guidance on using these external components. A major consideration in the selection of a PA and/or LNA are the limits imposed by the following standards:

- IEEE 802.15.4
- FCC 15.247
- RSS-210
- ETSI EN 300 328
- ARIB STD-T66

Other local regulations and limits may apply. Approval for an end product solution under these standards is done on a case by case basis. Freescale recommends that a competent approval body and/or a consultant in the field be consulted as early as possible in the design process. Additionally, Freescale cannot by held liable for the use of the information contained herein, which is meant to provide general guidance only.

All calculations contained in this note are based upon a nominal 0dBm output power from the transceiver. The detailed performance of the transceiver can be found in the respective device data sheet and/or reference manual.

2 General Requirements

The PA and LNA general requirements described in this note are limited to applications in the 2.4GHz ISM band.

2.1 IEEE 802.15.4 Parameters

The following parameters defined in the IEEE 802.15.4 standard are met or exceeded by the performance of the Freescale transceivers and should not be degraded by the addition of a PA in the transmit path:

- Tx maximum output power is -3dBm at the lower limit and are not specified for the upper limit. The regulatory bodies do specify an upper limit to the maximum output power, which will be covered in a later section.
- Carrier accuracy and modulation accuracy are not to exceed +/-40ppm.
- EVM cannot exceed 35%.
- Tx spectral density has to be less than -20dBc relative to carrier and less than -30dBm absolute power, both at +/-3.5MHz offset from highest average spectral power measured within +/-1MHz of carrier. Relative and absolute spectral powers are measured with a 100kHz bandwidth.

Tx power control range and Tx power step size are not explicitly set by the 802.15.4 standard. However, Section 6.7.6 states, "Devices should transmit lower power when possible in order to reduce interference to other devices and systems".

For any design that uses an external LNA, ensure that the design meets the requirements as described in the following sections of the IEEE 802.15.4 Standard:

- Section 6.5.3.4 (Jamming Resistance)
- Section 6.7.6 (Receiver Maximum Input Level)



2.2 Regulatory Standards (Transmitter Output Power)

The maximum allowed output power of the transmitter with the external PA is defined by the regulatory standards and is summarized in Table 1.

Geographical Region	Radiated Power (EIRP)	Conducted Power	Max Allowed Antenna Gain	Standard
-United States / Canada	-	1 W 30 dBm	6 dBi	FCC 15.247 RSS-210
Europe	100 mW (20 dBm)	-	0 dBi (Peak gain above 0 dBi reduces the allowable TX power by the same amount.)	EN 300 328
Japan	-	10 mW/MHz 10 dBm/MHz	2.14dBi for conducted test	ARIB STD-T66

Table 1. Max Transmitter Output Power as Defined by Regulatory Standards

In Figure 1, the output power limits for conducted measurements, as listed in Table 1, are superimposed on a measured 2480MHz modulated carrier with no external PA.





2.3 Regulatory Standards (Spurious Emissions)

The regulatory standards set limits on the spurious emissions and are summarized in Table 2. FCC and some ETSI standards tests are radiated measurements, which are affected by the antenna gain at the frequency of interest. Table 2 also lists FCC limits for a 100 percent duty cycle only. The FCC does allow for a reduction in duty cycles to a minimum of 10%, which translates to an increase on the spurious emissions limits.

NOTE

ETSI and ARIB do not allow any relaxation of limits for duty cycle.

Geographical Region	Radiated Power (EIRP)	Conducted Power	Relevant Frequency Bands	Standard
United States/Canada	-41.2 dBm/MHz	-	Restricted Bands: 2310 – 2390 MHz 2483.5 – 2500 MHz 4.5 – 5.15 GHz 7.25 – 7.75 GHz 10.6 – 12.7 GHz 14.47 – 14.5 GHz 17.7 – 21.4 GHz 22.01 – 23.12 GHz	FCC 15.247 RSS-210
	-	-20 dBc	All frequencies not listed in above cells.	-
	-36 dBm/MHz	-	30 MHz – 1 GHz	EN 300 328
_	-30 dBm/MHz	-	1 GHz – 12.75 GHz	-
Europe	-47 dBm/MHz	-	Restricted Bands: 1.8 – 1.9 GHz 5.15 GHz – 5.3 GHz	-
lanan	-	25 µW/MHz -16.02 dBm/MHz	2387 – 2400 MHz 2483.5 – 2496.5 MHz	ARIB STD-T66
Japan	-	2.5 μW/MHz -26.02 dBm/MHz	10 – 2387 MHz 2496.5 – 8000 MHz	-

Table 2	Max [·]	Transmitter	Spurious	Emissions a	s Defined	hv Re	dulatory	/ Standards
	IVIAN	manamiller	opunious		3 Denneu	Dyine	guiatory	Januarus

The strictest limitations to using an external PA are those imposed by the FCC on the frequencies directly adjacent to the upper and lower edges of the 2.4 GHz ISM band. As shown in Figure 2, the channel that most closely falls into an FCC restricted band is the upper channel at 2480MHz. There is more margin for the lower channel at 2405MHz.





Figure 2. Spurious Emissions Limits on Upper and Lower Channels

Figure 3 shows the 2480MHz modulated carrier in a 10MHz span. The spurious limits from the regulatory bodies are superimposed on the spectrum, which fails FCC spurious emission requirements for a 100% duty cycle. There is more margin available against the ETSI and ARIB requirements. The non-ideal behavior of the spectrum is due to the following:

- Modulation sideband spectral regrowth
- Phase noise
- Switching noise





Frequency (MHz) Figure 3. Spurious Emissions Limits on Modulated Spectrum (2480MHz)

Regulatory Body	Margin (dB)
FCC	none
ETSI	11
ARIB	29

Table 3. Margin to Regulatory Body Spurious Emission Limits

Even the perfect theoretical IEEE 802.15.4 waveform has limited margin vs. the FCC requirements for a 100% duty cycle.

If the duty cycle is reduced from 100%, then the spurious emissions limits are effectively increased and more transmitter output power is allowed for FCC requirements. The majority of IEEE 802.15.4 applications can make use of the increased spurious emissions limits due to extremely low duty cycles. Table 4 shows the increase in output gain that is allowable through duty cycle reduction.

Table 4. Margin with Various FCC Duty Cycles

FCC Duty Cycle	Margin (dB)
100%	none
30%	10
10%	20



20Db is the maximum relaxation allowed by the FCC for duty cycle.

If the application tolerates disuse or reduced power of the upper channels and the lowest channel, even more transmitter output power will be allowed. Table 5 and Figure 4 show these values.

Frequency Channel (MHz)	Margin (dB)
2470	12
2475	6
2480	none

 Table 5. Margin with Various Frequency Channels



Frequency (MHz) Figure 4. Increase in Output Power vs. Frequency Channel

Capability of operation on all channels is required to be fully IEEE 802.15.4 compliant. However, different transmit power levels can be used on different channels.

The addition of an external PA could result in harmonics that exceed the spurious emissions limits imposed by the regulatory bodies. For example, both the 2nd and 3rd harmonics fall in the FCC restricted spurious emissions bands. As the duty cycle is reduced, an increase in harmonic power is allowed as shown in Figure 5 for FCC requirements. Duty cycle reduction and/or the use of a low-pass or band-pass output filter may be necessary. There are small and efficient ceramic monolithic devices manufactured by a range



of suppliers. The manufacturers can assist in selecting the proper device for a given application. (See Section 4.3, "Ceramic Filters".) In some cases, a lumped-element LC filter may be adequate.



Frequency (MHz) Figure 5. Spurious Emissions Limits on 2nd and 3rd Harmonics

3 Practical Test Implications

The standards cited in this note specify the transmitter output power and spurious emissions limits that the unit under test is required to pass in order to be certified. At first glance, it appears to be simple exercise to calculate the maximum output power allowed, but there are a range of factors that complicate matters. The following sections describe these factors.

3.1 Antenna Gain

Some of the regulatory testing is performed as radiated tests, and the gain of the antenna at the frequency of interest becomes a factor in the measurements. Gain for an embedded antenna can vary considerably, from less than -5 dBi to more than 5 dBi, even on simple antennas. This could result in more than 10 dB of difference from one design or layout to another, even for an identical transmitter.

3.2 Measurement Accuracy

RF measurements are always subject to some tolerance. Even with careful calibration, conducted tests at two different test houses can show more than 2 dB of difference.



Radiated tests are subject to even higher tolerances, and the repeatability of these measurements is worse than conducted measurements.

3.3 Test Setup

The test set-up parameters (bandwidth, sweep time, trace parameters, etc) may significantly affect the measured values and cannot be controlled by Freescale, as these are determined by the particular test case and test house. Consequently, tests results vary considerably from one test house to another.

Freescale recommends that when a PA is used the relevant test house be contacted early in the design process and preliminary tests be performed on prototype samples. The measured results from the test house will indicate the power level that may be allowed in the final product.

3.4 PCB Layout and Shielding

Some harmonic emissions can radiate directly from PCB traces themselves. This is because a trace that is electrically short at 2.4 GHz may approach 1/4 or 1/2 wave at a harmonic frequency. This is especially true for the higher harmonics.

Also, a metal shield that is effective at 2.4 GHz may provide less attenuation at a harmonic frequency. This depends on the design itself and how it is attached.

3.5 Component Selection

Component selection can also be an important factor. For example, most ceramic monolithic baluns provide a degree of harmonic attenuation inherent to the design. However, the degree of attenuation can vary from one component vendor to another.

Another item to consider is that PA matching components built by different vendors may have identical performance at 2.4 GHz, but their performance at harmonic frequencies can vary a great deal. This means that identical parts from different vendors can produce different transmitter harmonic levels.

4 Device Examples

An external LNA may be used in addition to a PA to increase range. The LNA has the obvious advantage of not being constrained by the regulatory standards that strictly limit the transmitter output power. This section describes some example LNAs, PAs, and ceramic filters.

4.1 LNA Devices

The increase in receiver sensitivity with the use of an external LNA is determined by the gain and noise figure of the LNA. If the LNA gain is adequate (>10 dB), the noise figure of the LNA will be the primary factor in determining the achievable sensitivity; thus, it becomes important to use a low noise LNA transistor.

The MC1319x evaluation board has an on-board LNA with a gain of approximately 10.5 dB. Measured sensitivity without the LNA was –95 dBm while measured sensitivity with the LNA was –103 dBm.



The increase in sensitivity with the use of the LNA resulted in an increase in range. (See Freescale Application note, AN2902.) This characterization was performed with no obstructions (line of sight) in a remote outdoor setting. Remember, if range is limited due to ambient noise and EMI in the 2.4 GHz band, such as that from heavy WLAN traffic, then an LNA may be of limited benefit.

Vendor	Device	Gain	Noise Figure	Enable Pin?	Other Parameters
Freescale	MBC13720	12 dB	<3 dB	Yes	MMIC, low external parts count, bypass feature
NEC	NE661M04	13 dB	<1.6 dB	No	High performance, high frequency transistor
NEC	NE662M04	14.5 dB	<1.4	No	High performance, high frequency transistor
NEC	UPC8231TK	17.0 dB	<1.3 dB	Yes	MMIC, high gain
Infineon	BGA622	12 dB	<1.5 dB	No	Low external parts count
Infineon	BFP420	13.6 dB	<1.4 dB	No	High performance, high-frequency transistor
Phillips/NXP	BGA2012	11.5 dB	<2.5 dB	Yes	MMIC, low external parts count

Table 6. LNA Devices

Table 6 lists some LNA devices and some of their relevant specifications.

4.2 PA Devices

A suitable PA device should be capable of supplying the requested output power, and should not degrade the transmitted signal. Because O-QPSK modulation is used for IEEE 802.15.4, a linear PA is required to avoid an increase in the sidebands and EVM. A PA device designed for Bluetooth applications can be used, but the output power will have to be reduced from the device rating listed for a Bluetooth signal.

Harmonics will increase with the use of a PA and these will need to be filtered out.

Table 7 lists devices with their respective output 1 dB compression point. It may be possible to use these devices to the 1 dB compression point, but EVM and spurious emissions should always be checked for degradation compared to operation without a PA.

Vendor	Device	Output 1 dB Compression Point
Freescale	MBC13720	14 dBm
Freescale	MMG2401	>20 dBm
NEC	UPG2301TQ	>22 dBm



4.3 Ceramic Filters

Table 8 shows commonly selected output ceramic filters for the ISM band.

Vendor	Device
Murata	LFB182G45SG9B740
Johanson	2450BP18C100A
Johanson	2450BP41D100B

Table 8. Ceramic Filters

5 Modules

Modular designs are currently available from several suppliers that include an external PA and/or LNA. Freescale strongly recommends that a small quantity of these be obtained, so that performance of designs with an external LNA and/or PA can be evaluated quickly in the intended application.

In some cases, rather than develop a new design in house, it may be an advantage to purchase a modular design, or to license the design of an existing module.

The following is a partial list of companies that produce modules with the Freescale series of IEEE 802.15.4 transceivers:

- L.S. Research (www.lsr.com)
- Maxstream (www.maxstream.com)
- Panasonic (www.digikey.com)



How to Reach Us:

Home Page: www.freescale.com

F-mail support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor Technical Information Center, CH370 1300 N. Alma School Road Chandler, Arizona 85224 +1-800-521-6274 or +1-480-768-2130 support@freescale.com

Europe, Middle East, and Africa: Freescale Halbleiter Deutschland GmbH Technical Information Center Schatzbogen 7 81829 Muenchen, Germany +44 1296 380 456 (English) +46 8 52200080 (English) +49 89 92103 559 (German) +33 1 69 35 48 48 (French) support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd. Headquarters ARCO Tower 15F 1-8-1, Shimo-Meguro, Meguro-ku, Tokyo 153-0064, Japan 0120 191014 or +81 3 5437 9125 support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd. Technical Information Center 2 Dai King Street Tai Po Industrial Estate Tai Po, N.T., Hong Kong +800 2666 8080 support.asia@freescale.com

For Literature Requests Only:

Preescale Semiconductor Literature Distribution Center P.O. Box 5405 Denver, Colorado 80217 1-800-521-6274 or 303-675-2140 Fax: 303-675-2150 LDCForFreescaleSemiconductor@hibbertgroup.com

Document Number: AN2975 Rev. 1.0 02/2007

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2005, 2006, 2007. All rights reserved.

